ABSTRACT

A semiconductor package includes a circuit board, an interposer structure on the circuit board, a first semiconductor chip and a second semiconductor chip on the interposer structure, the first and the second semiconductor chips electrically connected to the interposer structure and spaced apart from each other, and a mold layer between the first and second semiconductor chips, the mold layer separating the first and second semiconductor chips. A slope of a side wall of the mold layer is constant as the side wall extends away from an upper side of the interposer structure, and an angle defined by a bottom side of the mold layer and the side wall of the mold layer is less than or equal to ninety degrees.

FIG. 2